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## ABSTRACT

When a heating plate (34) performs heat treatment on a substrate (W) by a wireless wafer (Ww) provided with a temperature detecting portion (41), a storing  
5 portion (42) and a controller (42), the temperature of the heating plate is measured readily and accurately while suppressing lowering of a heating operation efficiency due to a measuring operation. A temperature measurement start instruction is provided to the controller (42) of the wireless wafer (Ww) at a position in a wireless wafer carrier (Cw), and thereby the wireless wafer (Ww) starts temperature detection to store time-  
10 series data of the detected temperature value in the storing portion (42). The wireless wafer (Ww) is transferred to a heating unit through a predetermined transfer path. Based on a transportation time required for placing the wireless wafer (Ww) on the heating plate (34) and the time-series data of the detected temperature value in the storing portion (42), the time-series data of the detected temperature value obtained  
15 after the wireless wafer (Ww) is placed on the heating plate (34) is fetched.